

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claim 1 (Currently amended): A method for heat treating a plurality of conductive interconnect structures attached to a substrate, the method comprising the steps of:

providing a contactor comprising a substrate and a plurality of conductive interconnect structures;

placing the contactor in an oscillating electromagnetic field, the oscillating electromagnetic field heating the interconnect structures without substantially heating the substrate; and

maintaining the contactor in the oscillating electromagnetic field until each of the interconnect structures obtains a defined heat-treatment temperature substantially greater than an ambient temperature for a predetermined period of time sufficient to permanently ~~improve~~ change a mechanical operating property of the interconnect structure.

Claim 2 (Previously presented): The method according to Claim 1, wherein the interconnect structures are comprised of a ferromagnetic material.

Claim 3 (Previously presented): The method according to Claim 2, wherein the ferromagnetic material is a nickel-cobalt alloy.

Claim 4 (Original): The method according to Claim 2, further comprising tuning the oscillating electromagnetic field to selectively heat the ferromagnetic material.

Claim 5 (Original): The method according to Claim 1, wherein the maintaining step further comprises obtaining the heat-treatment temperature greater than 800°C.

Claim 6 (Original): The method according to Claim 1, wherein the maintaining step further comprises obtaining the heat-treatment temperature greater than 1300°C.

Claim 7 (Original): The method according to Claim 1, further comprising generating the oscillating electromagnetic field between a pair of parallel plates.

Claim 8 (Original): The method according to Claim 1, further comprising generating the oscillating electromagnetic field between arms of a hairpin coil.

Claim 9 (Original): The method according to Claim 1, further comprising generating the oscillating electromagnetic field using a coil comprised of a copper tube formed into a coil shape.

Claim 10 (Previously presented): The method according to Claim 1, further comprising tuning a frequency of the oscillating electromagnetic field to a resonant frequency of a field generator circuit.

Claim 11 (Previously presented): The method according to Claim 1, further comprising tuning a frequency of the oscillating electromagnetic field to between about 10 MHz-15 MHz.

Claim 12 (Previously presented): The method according to Claim 1, further comprising measuring a temperature of the interconnect structures by applying a heat-indicating paint to the plurality of interconnect structures prior to the maintaining step.

Claims 13-15 (Canceled)

Claim 16 (Currently amended): The method according to Claim 1 wherein the mechanical operating property of the interconnect structures ~~improved~~ changed is at least one of ~~improved~~ greater yield strength, ~~improved resiliency~~ greater resistance to fatigue, decreased brittleness, or ~~improved~~ greater hardness.

Claim 17 (Previously presented): The method according to Claim 1, wherein the contactor comprises an interposer and the plurality of conductive interconnect structures are disposed on opposing sides of the substrate.

Claim 18 (Previously presented): The method according to Claim 1, wherein the contactor is for contacting a semiconductor wafer.

Claim 19 (Previously presented): The method according to Claim 1, wherein the interconnect structures are springs.

Claim 20 (Currently amended): The method according to claim 19, wherein the mechanical operating property of the interconnect structures ~~improved~~ changed is a spring characteristic of the interconnect substrates.

Claim 21 (Previously presented): The method according to claim 1, wherein each of the interconnect structures is attached to a terminal on the substrate and comprises a contact tip disposed away from the substrate.

Claim 22 (Previously presented): The method according to claim 21 further comprising:  
removing the contactor from the oscillating electromagnetic field; and  
cooling the interconnect structures to the ambient temperature.

Claim 23 (Canceled )

Claim 24 (New): The method of claim 1, wherein the maintaining step comprises heating the interconnect structures to a temperature that is less than the melting temperature of the interconnect structures.

Claim 25 (New): The method of claim 1, wherein the oscillating electromagnetic field induces electrical currents in the interconnect structures.

Claim 26 (New): A method comprising:

providing a contactor comprising a substrate and a plurality of electrically conductive probes, each probe comprising a base portion attached to the contactor, a tip portion spaced from the contactor, and a body portion between the base portion and the tip portion, wherein said probes are able to make electrical connections between said contactor and an electronic device; and

placing for a period of time the contactor in an oscillating electromagnetic field having sufficient strength to induce electrical currents in the probes to heat the probes at least to a particular temperature,

wherein the period of time and the particular temperature are sufficient to change permanently at least one mechanical operating property of the probes, and the at least one mechanical operating property is one of increased yield strength, increased resistance to fatigue, decreased brittleness, or increased hardness.

Claim 27 (New): The method of claim 26, wherein the providing comprises making the probes, wherein the making the probes comprises:

attaching wires to terminals of the contactor, and  
over coating the wires with an over coat material.

Claim 28 (New): The method of claim 26, wherein the providing comprises making the probes, wherein the making the probes comprises depositing at least one material in openings in a plurality of masking layers patterned to define at least a portion of a shape of said probes.

Claim 29 (New): The method of claim 26, wherein the providing comprises making the probes, wherein the making the probes comprises:

depositing a material in first openings in a first masking layer to form said base portions of said probes,

depositing a material in second openings in a second masking layer to form said body portions of said probes, and

depositing a material in third openings in a third masking layer to form said tip portions of said probes.